



Features

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- ESD Protected Up To 2kV
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

P-CHANNEL ENHANCEMENT MODE MOSFET

Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Terminal Connections: See Diagram Below
- Weight: 0.009 grams (Approximate)

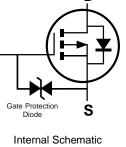
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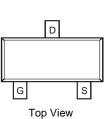




SOT23

Top View





Ordering Information (Note 5 & 6)

Part Number	Compliance	Case	Packaging
DMP2035U-7	Standard	SOT23	3,000 / 7" Tape & Reel
DMP2035UQ-7	Automotive	SOT23	3,000 / 7" Tape & Reel
DMP2035U-13	Standard	SOT23	10,000 / 13" Tape & Reel

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Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

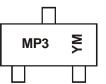
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to https://www.diodes.com/quality/.

5. The ESD gate protection diode is only designed to protect against ESD events. No gate-source voltage greater than the maximum V_{GSS} rating (given on page 2) can be applied.

For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



 $\begin{array}{l} MP3 = Product \mbox{ Type Marking Code} \\ YM = Date \mbox{ Code Marking} \\ Y \mbox{ or } \overline{Y} = Year \mbox{ (ex: } F = 2018) \\ M = Month \mbox{ (ex: } 9 = September) \end{array}$

Date Code Key

Year	2009	~	2017	2018	3 201	9 20	20 2	021	2022	2023	2024	2025
Code	W	~	E	F	G	ł	4		J	K	L	М
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Drain-Source Voltage		V _{DSS}	-20	V	
Gate-Source Voltage	V _{GSS}	±10	V		
		$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	۱ _D	-4.9 -4.0	А
Pulsed Drain Current (Note 9)			I _{DM}	-24	A
Maximum Continuous Body Diode Forward Curren	ls	-1.2	A		
Pulsed Body Diode Forward Current (Note 9)		lsм	-24	A	

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 7)	PD	0.81	W
Thermal Resistance, Junction to Ambient (Note 7)	R _{0JA}	153.5	°C/W
Total Power Dissipation (Note 8)	PD	1.2	W
Thermal Resistance, Junction to Ambient (Note 8)	R _{0JA}	100	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 10)	-						
Drain-Source Breakdown Voltage	BV _{DSS}	-20		_	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	—	-1.0	μA	$V_{DS} = -20V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±10	μA	$V_{GS} = \pm 8V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 10)							
Gate Threshold Voltage	V _{GS(TH)}	-0.4	-0.7	-1.0	V	$V_{DS} = V_{GS}, I_D = -250 \mu A$	
			23	35		$V_{GS} = -4.5V, I_D = -4.0A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	—	30 41	45 62	mΩ	$V_{GS} = -2.5V, I_D = -4.0A$	
						$V_{GS} = -1.8V, I_D = -2.0A$	
Forward Transfer Admittance	Y _{fs}	_	14	_	S	$V_{DS} = -5V, I_D = -4A$	
Diode Forward Voltage	V _{SD}		-0.7	-1.0	V	$V_{GS} = 0V, I_{S} = -1A$	
DYNAMIC CHARACTERISTICS (Note 11)	·		•		•	÷	
Input Capacitance	C _{iss}	_	1,610		pF		
Output Capacitance	Coss	_	157	—	pF	└ V _{DS} = -10V, V _{GS} = 0V - f = 1.0MHz	
Reverse Transfer Capacitance	Crss	_	145	—	pF		
Gate Resistance	Rg	_	9.45	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$	
Total Gate Charge	Qg	_	15.4	_	nC		
Gate-Source Charge	Q _{gs}		2.5	_	nC	$V_{GS} = -4.5V, V_{DS} = -10V,$	
Gate-Drain Charge	Q _{gd}		3.3	_	nC	$I_D = -4A$	
Turn-On Delay Time	t _{D(ON)}	_	16.8		ns		
Turn-On Rise Time	t _R	_	12.4		ns	V _{DS} = -10V, V _{GS} = -4.5V,	
Turn-Off Delay Time	t _{D(OFF)}	_	94.1		ns	$R_L = 10\Omega, R_g = 6.0\Omega, I_D = -1A$	
Turn-Off Fall Time	tF	_	42.4		ns	7	

Notes: 7. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

8. Device mounted on FR-4 substrate PC board, 2oz copper, with 25mm X 25mm square copper plate.

9. Repetitive rating, pulse width limited by junction temperature.

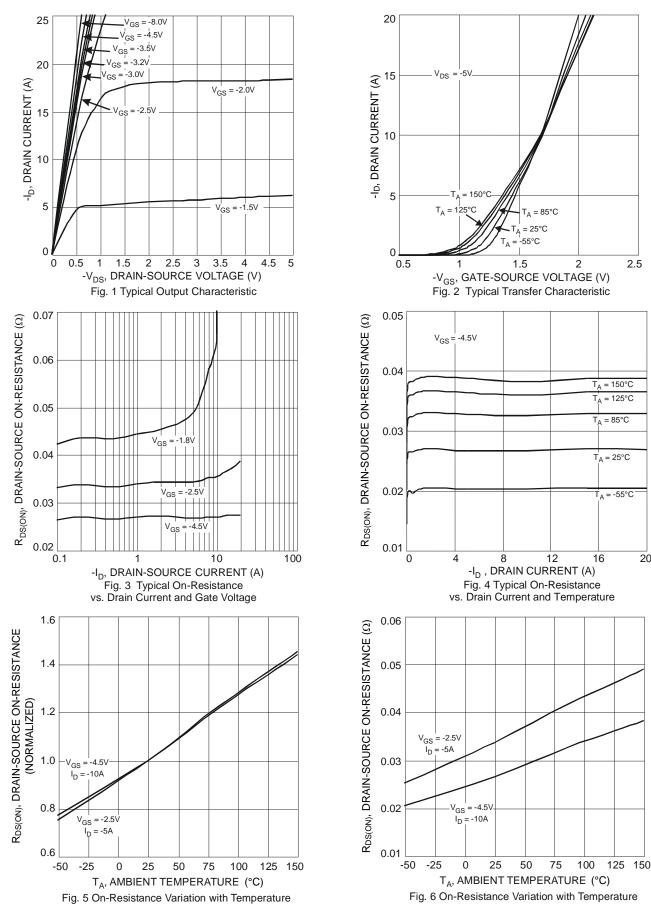
10. Short duration pulse test used to minimize self-heating effect.

11. Guaranteed by design. Not subject to product testing.



2.5

20







150°C

125⁶C

1.2

「_∧ = 150°C

= 125°C TΔ

T_Δ = 85°C

T_A = 25°C

18 20

= 85°C

 $T_A = 25^{\circ}C$

6

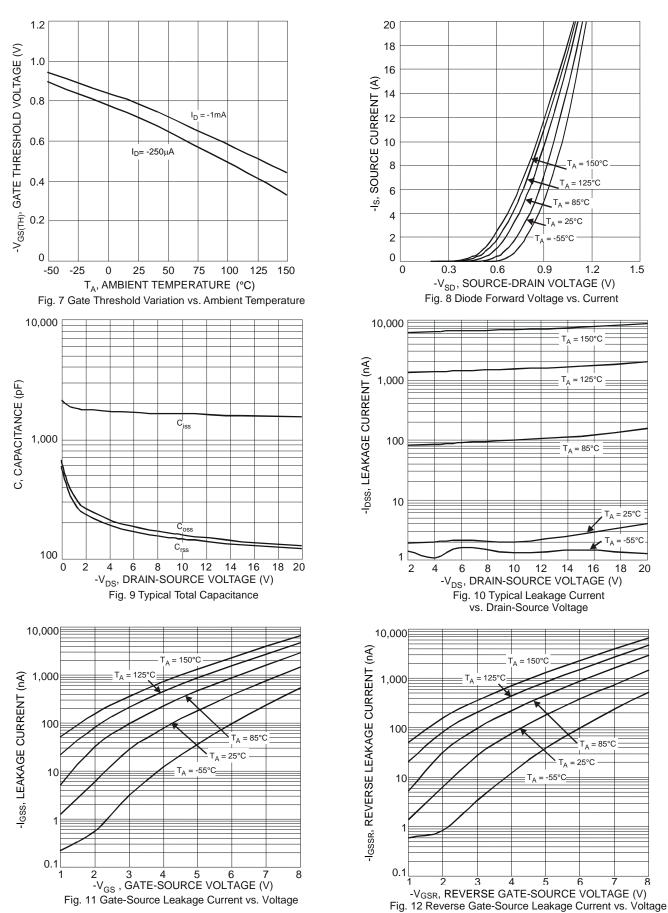
-55°C

1.5

= 85°C

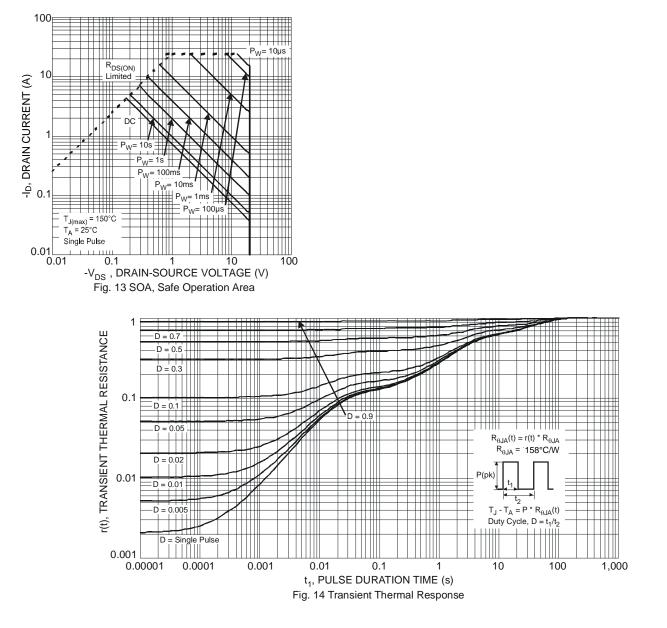
25°C

-55°C







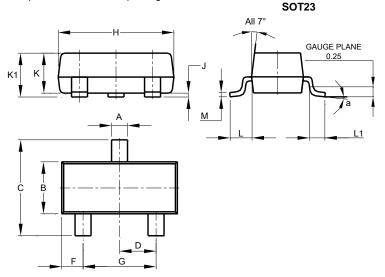




DMP2035U

Package Outline Dimensions

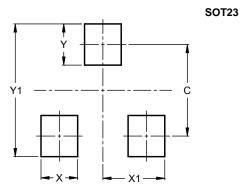
Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT23							
Dim	Min	Max	Тур				
Α	0.37	0.51	0.40				
В	1.20	1.40	1.30				
С	2.30	2.50	2.40				
D	0.89	1.03	0.915				
F	0.45	0.60	0.535				
G	1.78	2.05	1.83				
Н	2.80 3.00		2.90				
J	0.013	0.10	0.05				
K	0.890	1.00	0.975				
K1	0.903	1.10	1.025				
L	0.45	0.61	0.55				
L1	0.25	0.55	0.40				
М	0.085	0.150	0.110				
а	0°	8°					
All Dimensions in mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)			
С	2.0			
Х	0.8			
X1	1.35			
Y	0.9			
Y1	2.9			



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